

September 2009

# NC7SZ126 TinyLogic<sup>®</sup> UHS Buffer with Three-State Output

#### **Features**

- Ultra-High Speed: t<sub>PD</sub> 2.6ns (Typical) into 50pF at 5V V<sub>CC</sub>
- High Output Drive: ±24mA at 3V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range: 1.65V to 5.5V
- Matches Performance of LCX Operated at 3.3V V<sub>CC</sub>
- Power Down High-Impedance Inputs/Outputs
- Over-Voltage Tolerance Inputs Facilitate 5V to 3V Translation
- Proprietary Noise/EMI Reduction Circuitry
- Ultra-Small MicroPak™ Packages
- Space-Saving SOT23 and SC70 Packages

## **Description**

The NC7SZ126 is single buffer with three-State output from Fairchild's Ultra-High Speed (UHS) series of TinyLogic®. The device is fabricated with advanced CMOS technology to achieve ultra-high speed with high output drive while maintaining low static power dissipation over a broad  $V_{\rm CC}$  operating range. The device is specified to operate over the 1.65V to 5.5V  $V_{\rm CC}$  operating range. The inputs and output are high impedance above ground when  $V_{\rm CC}$  is 0V. Inputs tolerate voltages up to 6V, independent of  $V_{\rm CC}$  operating voltage. The output tolerates voltages above  $V_{\rm CC}$  in the 3-State condition.

## **Ordering Information**

Part Number	Top Mark	<b>©</b> Eco Status	Package	Packing Method
NC7SZ126M5X	7Z26	RoHS	5-Lead SOT23, JEDEC MO-178 1.6mm	3000 Units on Tape & Reel
NC7SZ126P5X	Z26	RoHS	5-Lead SC70, EIAJ SC-88a, 1.25mm Wide	3000 Units on Tape & Reel
NC7SZ126L6X	FF	RoHS	6-Lead MicroPak™, 1.00mm Wide	5000 Units on Tape & Reel
NC7SZ126FHX	FF	Green	6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

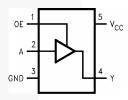
Por Fairchild's definition of Eco Status, please visit: <a href="http://www.fairchildsemi.com/company/green/rohs\_green.html">http://www.fairchildsemi.com/company/green/rohs\_green.html</a>.

## **Connection Diagrams**



Figure 1. Logic Symbol

## **Pin Configurations**





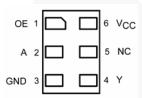


Figure 3. MicroPak (Top Through View)

## **Pin Definitions**

Pin # SC70 / SOT23	Pin # MicroPak	Name	Description	
1	1	OE	Input	
2	2	А	Input	
3	3	GND	Ground	
4	4	Υ	Output	
5	6	Vcc	Supply Voltage	
	5	NC	No Connect	

## **Function Table**

Inp	uts	Output
OE	Α	Out Y
Н	L	L
Н	Н	Н
L	X	Z

H = HIGH Logic Level

L = LOW Logic Level

X = HIGH or LOW Logic Level

Z = HIGH Impedance State

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Para	ameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage		-0.5	6.0	V
V <sub>IN</sub>	DC Input Voltage		-0.5	6.0	V
V <sub>OUT</sub>	DC Output Voltage		-0.5	6.0	V
I	DC Input Diode Current	V <sub>IN</sub> < -0.5V		-50	mA
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> > 6.0V		+20	IIIA
1	DC Output Diada Current	V <sub>OUT</sub> < -0.5V		-50	mA.
l <sub>OK</sub>	DC Output Diode Current	$V_{OUT} > 6V, V_{CC} = GND$		+20	IIIA
l <sub>out</sub>	DC Output Current			±50	mA
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current			±50	mA
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C
$T_J$	Junction Temperature Under B	ias		+150	°C
$T_L$	Junction Lead Temperature (Se	oldering, 10 Seconds)		+260	°C
		SOT-23		200	
$P_{D}$	Power Dissipation at +85°C	SC70-5		150	mW
FD	Fower Dissipation at +65 C	MicroPak-6	\ \	130	IIIVV
		MicroPak2-6	120		
ESD	Human Body Model, JEDEC:JESD22-A114			4000	V
ESD	Charge Device Model, JEDEC:	JESD22-C101		2000	

## **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit	
V <sub>CC</sub>	Supply Voltage Operating		1.65	5.50	V	
V CC	Supply Voltage Data Retention		1.50	5.50	7 °	
V <sub>IN</sub>	Input Voltage		0	5.5	V	
V	Output Valtage	Active State	0	Vcc	V	
V <sub>OUT</sub>	Output Voltage	Three-State	0	5.5	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
T <sub>A</sub>	Operating Temperature		-40	+85	°C	
		V <sub>CC</sub> =1.8V, 2.5V ± 0.2V	0	20		
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Times	$V_{CC} = 3.3 V \pm 0.3 V$	0	10	ns/V	
		$V_{CC}=5.0V \pm 0.5V$	0	5		
		SOT-23		300		
0	Thermal Desistance	SC70-5		425	0000	
$\theta_{\sf JA}$	Thermal Resistance	MicroPak-6		500	°C/W	
		MicroPak2-6		560		

#### Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

## **DC Electrical Characteristics**

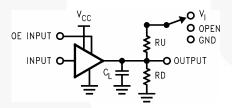
0	D	.,	C Conditions		T <sub>A</sub> =+25°C		T <sub>A</sub> =-40 to +85°C		Units
Symbol	Symbol Parameter V <sub>0</sub>	V <sub>CC</sub> Conditions		Min.	Тур.	Max.	Min.	Max.	Units
	HIGH Level	1.65 to 1.95		0.75V <sub>CC</sub>			0.75V <sub>CC</sub>		\/
$V_{IH}$	Input Voltage	2.30 to 5.50		0.70V <sub>CC</sub>			0.70V <sub>CC</sub>		V
	LOW Level	1.65 to 1.95				0.25V <sub>CC</sub>		0.25V <sub>CC</sub>	\ /
$V_{IL}$	Input Voltage	2.30 to 5.50				0.30V <sub>CC</sub>		0.30V <sub>CC</sub>	V
		1.65		1.55	1.65		1.55		
		1.80		1.70	1.80		1.70		
		2.30	V <sub>IN</sub> =V <sub>IH</sub> , I <sub>OH</sub> =-100µA	2.20	2.30		2.20		
		3.00		2.90	3.00		2.90		
	HIGH Level	4.50		4.40	4.50		4.40		V
$V_{OH}$	Output Voltage	1.65	I <sub>OH</sub> =-4mA	1.29	1.52		1.29		V
		2.30	I <sub>OH</sub> =-8mA	1.90	2.15		1.90		
		3.00	I <sub>OH</sub> =-16mA	2.40	2.80		2.40		
		3.00	I <sub>OH</sub> =-24mA	2.30	2.68		2.30		
		4.50	I <sub>OH</sub> =-32mA	3.80	4.20		3.80		
		1.65		(	0.00	0.10		0.10	
	7	1.80			0.00	0.10		0.10	
	7/5	2.30	V <sub>IN</sub> =V <sub>IL</sub> ,I <sub>OL</sub> =100µA		0.00	0.10		0.10	
		3.00			0.00	0.10		0.10	
	LOW Level	4.50			0.00	0.10	1	0.10	
$V_{OL}$	Output Voltage	1.65	I <sub>OL</sub> =4mA		0.80	0.24		0.24	V
		2.30	I <sub>OL</sub> =8mA		0.10	0.30		0.30	
		3.00	I <sub>OL</sub> =16mA		0.15	0.40		0.40	
		3.00	I <sub>OL</sub> =24mA		0.22	0.55		0.55	
		4.50	I <sub>OL</sub> =32mA		0.22	0.55		0.55	
I <sub>IN</sub>	Input Leakage Current	0 to 5.5	V <sub>IN</sub> =5.5V, GND			±1		±10	μΑ
loz	3-STATE Output Leakage	0 to 5.5	V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub> V <sub>O</sub> =V <sub>CC</sub> or GND			±1		±10	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	0	V <sub>IN</sub> or V <sub>OUT</sub> =5.5V			1		10	μΑ
Icc	Quiescent Supply Current	1.65 to 5.50	V <sub>IN</sub> =5.5V, GND			2		20	μA

## **AC Electrical Characteristics**

Cumbal	Parameter	Conditions	Conditions		Γ <sub>A</sub> =25°	С	T <sub>A</sub> =-40 1	to +85°C	Units	Figure
Symbol	Parameter	V <sub>CC</sub>	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	rigure
		1.65		2.0	6.4	13.2	2.0	13.8		
		1.80	C <sub>L</sub> =15pF,	2.0	5.3	11.0	2.0	11.5		
		$2.50 \pm 0.20$	$R_D=1M\Omega$	8.0	3.4	7.5	0.8	8.0		
$t_{PLH,}t_{PHL}$	Propagation Delay	$3.30 \pm 0.30$	S <sub>1</sub> =OPEN	0.5	2.5	5.2	0.5	5.5	ns	Figure 4
7 211, 7 112	., ., .,	$5.00 \pm 0.50$		0.5	2.1	4.5	0.5	4.8		Figure 6
		$3.30 \pm 0.30$	C <sub>L</sub> =50pF,	1.5	3.2	5.7	1.5	6.0		
		5.00 ± 0.50	$R_D=500\Omega$ $S_1=OPEN$	0.8	2.6	5.0	0.8	5.3		
		1.65	$\begin{array}{c} C_L \!\!=\!\! 50 p F, \\ R_D \!\!=\!\! 500 \Omega \\ RU \!\!=\!\! 500 \Omega \\ S_1 \!\!=\!\! GND \text{ for } t_{PZH} \\ S_1 \!\!=\!\! V_{IN} \text{ for } t_{PZL} \\ V_{IN} \!\!=\!\! 2^{\bullet} \!$	2.0	8.4	15.0	2.0	15.6	ns	
		1.80		2.0	6.1	11.5	2.0	12.0		
$t_{PZL,}t_{PZH}$	Output Enable Time	$2.50 \pm 0.20$		1.5	3.8	8.0	1.5	8.5		
		$3.30 \pm 0.30$		1.5	3.2	5.7	1.5	6.0		
		$5.00 \pm 0.50$		0.8	2.3	5.0	0.8	5.3		Figure 4
		1.65	C <sub>L</sub> =50pF,	2.0	6.5	13.2	2.0	14.5	115	Figure 6
		1.80	$R_D=500\Omega$	2.0	5.6	11.0	2.0	12		
$t_{\text{PLZ}}, t_{\text{PHZ}}$	Output Disable Time	$2.50 \pm 0.20$	RU=500Ω S <sub>1</sub> =GND for $t_{PHZ}$	1.0	4.0	8.0	1.0	8.5		
		$3.30 \pm 0.30$	$S_1 = V_{IN}$ for $t_{PLZ}$	1.0	3.5	5.7	1.0	6.0		
	$5.00 \pm 0.50$	V <sub>IN</sub> =2•V <sub>CC</sub>	0.5	2.5	4.7	0.5	5.0			
C <sub>IN</sub>	Input Capacitance	0.00			4	_			pF	
C <sub>OUT</sub>	Output Capacitance	0.00			8				pF	
$C_{PD}$	Power Dissipation	3.30			17				pF	Figure 5
OPD	Capacitance <sup>(2)</sup>	5.00			24				ρı	i igule 5

#### Note:

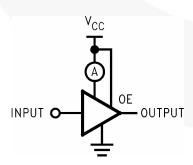
 C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output lading and operating at 50% duty cycle. C<sub>PD</sub> is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub>=(C<sub>PD</sub>)(V<sub>CC</sub>)(f<sub>IN</sub>)+(I<sub>CC</sub>static).



#### Note:

3.  $C_L$  includes load and stray capacitance. Input PRR=1.0MHz,  $t_W$ =500ns

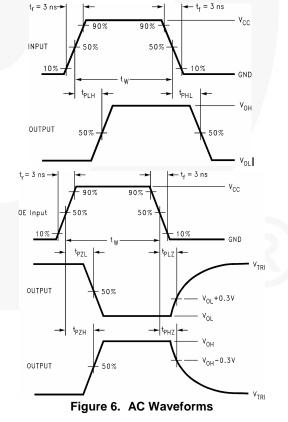
Figure 4. AC Test Circuit



#### Note:

 Input=AC Waveform; t<sub>r</sub>=t<sub>f</sub>=1.8ns; PRR=10MHz; Duty Cycle=50%.

Figure 5. I<sub>CCD</sub> Test Circuit



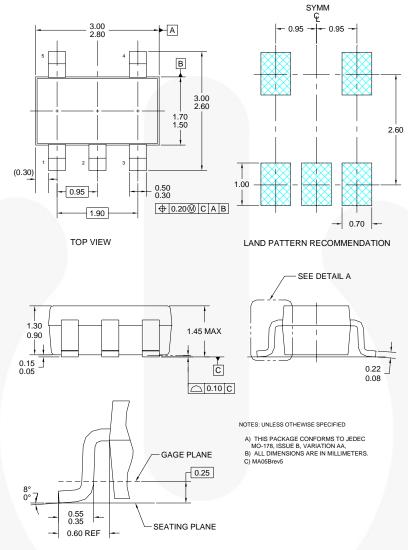


Figure 7. 5-Lead SOT23, JEDEC MO-178 1.6mm

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### **Tape and Reel Specifications**

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/packaging/SOT23-5L\_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
M5X	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

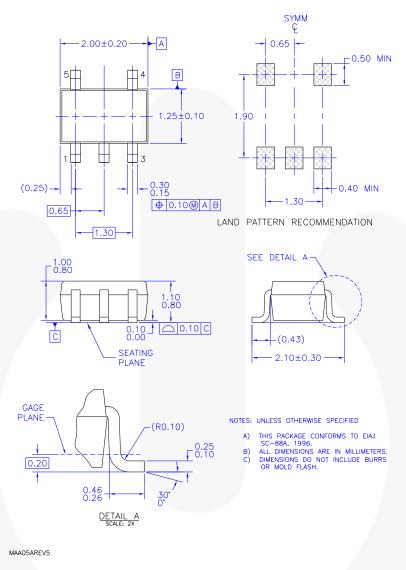


Figure 8. 5-Lead, SC70, EIAJ SC-88a, 1.25mm Wide

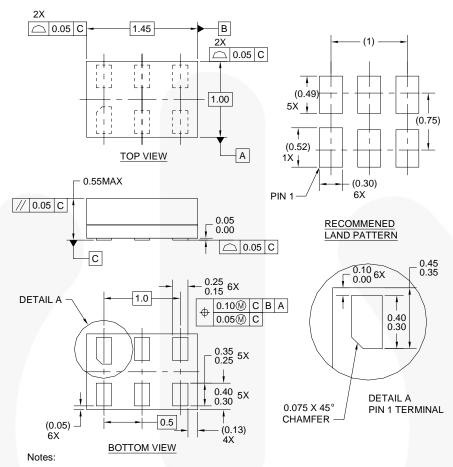
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Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status	
	Leader (Start End)	125 (Typical)	Empty	Sealed	
P5X	Carrier	3000	Filled	Sealed	
	Trailer (Hub End)	75 (Typical)	Empty	Sealed	



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06AREVC

Figure 9. 6-Lead, MicroPak™, 1.0mm Wide

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Package Designator	Package Designator Tape Section		Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
L6X	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

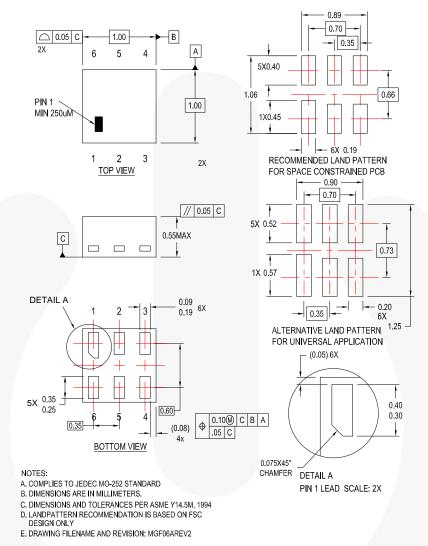


Figure 10.6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch

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Package Designator	Tape Section Cavity Number		Cavity Status	Cover Type Status	
	Leader (Start End)	125 (Typical)	Empty	Sealed	
FHX	Carrier	5000	Filled	Sealed	
	Trailer (Hub End)	75 (Typical)	Empty	Sealed	





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#### Definition of Terms

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Datasheet Identification	Product Status	Definition				
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.				
		Data sheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.				
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.				
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# AMEYA360 Components Supply Platform

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